



Material Content Data Sheet



Sales Product Name		BTS50055-1TMC		Issued		24. January 2018		
MA#		MA000842968						
Package		PG-TO220-7-4		Weight*		1531.06 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.514	1.01	1.01	10133	10133
leadframe	non noble metal	iron	7439-89-6	0.804	0.05		525	
	inorganic material	phosphorus	7723-14-0	0.241	0.02		158	
	non noble metal	copper	7440-50-8	802.842	52.44	52.51	524369	525052
wire	non noble metal	aluminium	7429-90-5	5.337	0.35	0.35	3486	3486
encapsulation	organic material	carbon black	1333-86-4	8.690	0.57		5676	
	plastics	epoxy resin	-	95.591	6.24		62435	
	inorganic material	silicondioxide	60676-86-0	475.060	31.03	37.84	310282	378393
leadfinish	non noble metal	tin	7440-31-5	12.090	0.79	0.79	7897	7897
plating	non noble metal	nickel	7440-02-0	0.216	0.01	0.01	141	142
	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
glue	plastics	Polyimide	26023-21-2	0.217	0.01	0.01	142	142
solder	noble metal	silver	7440-22-4	0.203	0.01		132	
	non noble metal	tin	7440-31-5	0.162	0.01		106	
	non noble metal	lead	7439-92-1	7.743	0.51	0.53	5057	5295
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.94	6.95	69370	69460
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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